PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4351541

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
WALID M. HAFEZ	06/20/2014
CHIA-HONG JAN	06/20/2014

RECEIVING PARTY DATA

Name:	INTEL CORPORATION
Street Address:	2200 MISSION COLLEGE BOULEVARD
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95052

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15409065

CORRESPONDENCE DATA

Fax Number: (303)740-6962

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 408-720-8300
Email: Connie_Bursey@bstz.com
Correspondent Name: BLAKELY SOKOLOFF TAYLOR & ZAFMAN LLP
Address Line 1: 1279 OAKMEAD PARKWAY
Address Line 4: SUNNYVALE, CALIFORNIA 94085-4040

ATTORNEY DOCKET NUMBER:	42P67945USC
NAME OF SUBMITTER:	CONNIE BURSEY
SIGNATURE:	/Connie Bursey/
DATE SIGNED:	04/04/2017

Total Attachments: 2
source=P67945USC-Assignment#page1.tif
source=P67945USC-Assignment#page2.tif

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

HAFEZ, WALID M.; JAN, CHIA-HONG

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95052 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the International application entitled:

SOLID-SOURCE DIFFUSED JUNCTION FOR FIN-BASED ELECTRONICS

(I hereby authorize and request my attorney, associated with Customer Number 45209, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on ______________________________ as

International Application Number ____________________ and

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said International application and all related applications (e.g. national phase applications, divisional applications, continuation applications, reexaminations, reissues, and the like) that have been or shall be filed in the United States and/or all foreign countries on said inventions and improvements, as well as in and to all rights of priority resulting from the filing of said International application;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Walid Hafez
HAFEZ, WALID M.

6/20/14
(Today's Date)

JAN, CHIA-HONG

6/20/14
(Today's Date)

Inventor 3

(Today's Date)

Inventor 4

(Today's Date)

Inventor 5

(Today's Date)